



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea7k3f40c2

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Electrical Characteristics Page 5

Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) (3)	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
V_{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
V_{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V _I	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	_	0	_	V _{CCIO}	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T _J	Operating junction temperature	Industrial	-40	_	100	°C

Page 6 Electrical Characteristics

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
t _{RAMP} Power supply ramp time		Standard POR	200 μs	_	100 ms	_
t _{RAMP}	Fower supply rainp line	Fast POR	200 μs	_	4 ms	_

Notes to Table 6:

- (1) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit	
V _{CCA_GXBL}	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V	
(1), (3)	side)	७४, ७७, ७१	2.375	2.5	2.625	V	
V _{CCA_GXBR}	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V	
$(1), (\overline{3})$	side)	রম, রহ	2.375	2.5	2.625	V	
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V	
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V_{CCHIP_R}	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V	
V _{CCHSSI_R}	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V	
			0.82	0.85	0.88		
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V	
(2)	Treceiver arialog power supply (left side)	un, us, ui	0.97	1.0	1.03	V	
			1.03	1.05	1.07		

Electrical Characteristics Page 9

I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

Table 9. I/O Pin Leakage Current for Stratix V Devices (1)

Symbol	Description	Conditions	Min	Тур	Max	Unit
I	Input pin	$V_I = 0 V to V_{CCIOMAX}$	-30	_	30	μΑ
I _{OZ}	Tri-stated I/O pin	$V_0 = 0 V \text{ to } V_{\text{CCIOMAX}}$	-30	_	30	μΑ

Note to Table 9:

(1) If $V_0 = V_{CCIO}$ to $V_{CCIOMax}$, 100 μA of leakage current per I/O is expected.

Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

			V _{CCIO}										
Parameter	Symbol	Conditions	1.2	2 V	1.9	5 V	1.8	B V	2.	5 V	3.0	V	Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (maximum)	22.5	_	25.0	_	30.0	_	50.0	_	70.0	_	μА
High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (minimum)	-22.5	_	-25.0	_	-30.0	_	-50.0	—	-70.0		μА
Low overdrive current	I _{ODL}	0V < V _{IN} < V _{CCIO}	_	120	_	160	_	200	_	300	_	500	μА
High overdrive current	I _{ODH}	0V < V _{IN} < V _{CCIO}	_	-120	_	-160	_	-200	_	-300	_	-500	μА
Bus-hold trip point	V _{TRIP}	_	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 1 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C 1	C2,I2	C3,I3, I3YY	C4,I4	Unit
25-Ω R _S	Internal series termination with calibration (25- Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Electrical Characteristics Page 11

Symbol Description			Resistance Tolerance					
		Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit	
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%	
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.2 V	±35	±35	±50	±50	%	
100-Ω R _D	Internal differential termination (100-Ω setting)	V _{CCPD} = 2.5 V	±25	±25	±25	±25	%	

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

Equation 1. OCT Variation Without Recalibration for Stratix V Devices (1), (2), (3), (4), (5), (6)

$$R_{OCT} = R_{SCAL} \Big(1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \Big)$$

Notes to Equation 1:

- (1) The R_{OCT} value shows the range of OCT resistance with the variation of temperature and V_{CCIO} .
- (2) R_{SCAL} is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V_{CCIO} at power-up.
- (5) dR/dT is the percentage change of R_{SCAL} with temperature.
- (6) dR/dV is the percentage change of R_{SCAL} with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.0297	
	OCT variation with voltage without recalibration	2.5	0.0344	
dR/dV		1.8	0.0499	%/mV
		1.5	0.0744	
		1.2	0.1241	

Page 12 Electrical Characteristics

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.189	
	OCT variation with temperature without recalibration	2.5	0.208	
dR/dT		1.8	0.266	%/°C
		1.5	0.273	1
		1.2	0.317	

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to $85^\circ\text{C}.$

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Symbol Description		Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

Page 16 Electrical Characteristics

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

I/O		V _{CCIO} (V)		V _{DIF(I}	_{DC)} (V)	(V) V _{X(AC)} (V)				V _{CM(DC)} (V)	V _{DIF(AC)} (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	_	0.5* V _{CCIO}	_	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V _{CCIO} - 0.12	0.5* V _{CCIO}	0.5*V _{CCIO} + 0.12	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.44	0.44

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	_{CIO} (V)	(10)		V _{ID} (mV) ⁽⁸⁾			$V_{ICM(DC)}$ (V)		Vo	D (V) (6)	V _{OCM} (V) ⁽⁶⁾		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Trar	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Table 23 on page 18.													
2.5 V	2.375	2.5	2.625	100	V _{CM} =	_	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247		0.6	1.125	1.25	1.375
LVDS (1)	2.373	2.3	2.023	100	1.25 V		1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_		_
RSDS (HIO) ⁽²⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) (3)	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_	_	0.6	D _{MAX} ≤ 700 Mbps	1.8	_	_	_	_	_	_
), (9)	_	_	_	300	_	_	1	D _{MAX} > 700 Mbps	1.6	_	_	_	_	_	_

Notes to Table 22:

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.
- (6) RL range: $90 \le RL \le 110 \Omega$.
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 $\rm V.$

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus[®] II PowerPlay Power Analyzer feature.

Electrical Characteristics Page 17



You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V _{MAX} ⁽⁵⁾	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin		_	1.2	_	_	1.2	_	_	1.2	
Absolute V _{MIN}	_	-0.4		_	-0.4		_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V _{ICM} (AC clock pin		1050/	1000/90	00/850 ⁽²⁾	1050/1000/900/850 (2)			1050/	00/850 ⁽²⁾	mV	
coupled) ⁽³⁾	RX reference clock pin	1.	.0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	V
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) ⁽²⁰⁾	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120		_	-120		_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R _{REF} (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_				
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 6 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed e 1	Trar	sceive Grade	r Speed 2	Tran	sceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	ı	ı	500	_	ı	500	_	_	500	ps
CMU PLL											
Supported Data Range	_	600	_	12500	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs
t _{pll_lock} (16)	_	_	_	10	_	_	10	_	_	10	μs
ATX PLL											
	VCO post-divider L=2	8000		14100	8000		12500	8000	_	8500/ 10312.5 (24)	Mbps
Cummonted Data	L=4	4000	_	7050	4000	_	6600	4000	_	6600	Mbps
Supported Data Rate Range	L=8	2000	_	3525	2000	_	3300	2000	_	3300	Mbps
S	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	1000	_	1762.5	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs
t _{pll_lock} (16)				10	_		10			10	μs
fPLL											
Supported Data Range	_	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs

Table 26 shows the approximate maximum data rate using the 10G PCS.

Table 26. Stratix V 10G PCS Approximate Maximum Data Rate (1)

Mode ⁽²⁾	Transceiver	PMA Width	64	40	40	40	32	32
Widue (2)	Speed Grade	PCS Width	64	66/67	50	40	64/66/67	32
	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5
	۷	C3, I3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88
FIFO or Register		C1, C2, C2L, I2, I2L core speed grade						
	3	C3, I3, I3L core speed grade			8.5	Gbps		
	3	C4, I4 core speed grade	е					
		I3YY core speed grade	10.3125 Gbps					

Notes to Table 26:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

Figure 2 shows the differential transmitter output waveform.

Figure 2. Differential Transmitter Output Waveform

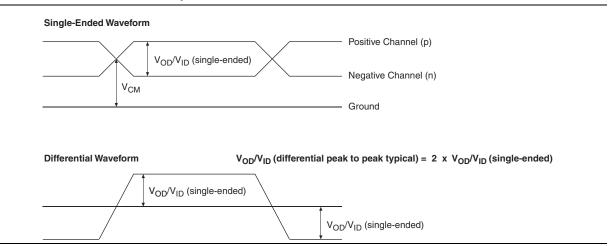


Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)



Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23.

Table 28 lists the Stratix V GT transceiver specifications.

Page 34 Switching Characteristics

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (1)

Symbol/	Symbol/ Description Conditions		Transceivei peed Grade		T Sp	Unit		
Description			Тур	Max	Min	Тур	Max	
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs

Notes to Table 28:

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9) t_{LTB} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10) tLTD is time required for the receiver CDR to start recovering valid data after the rx is lockedtodata signal goes high.
- (11) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (12) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (13) tpll powerdown is the PLL powerdown minimum pulse width.
- (14) tpll lock is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (17) For ES devices, RREF is 2000 Ω ±1%.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

Table 29 shows the $\ensuremath{V_{\text{OD}}}$ settings for the GT channel.

Table 29. Typical V_{0D} Setting for GT Channel, TX Termination = 100 Ω

Symbol	V _{OD} Setting	V _{op} Value (mV)
	0	0
	1	200
V _{op} differential peak to peak typical ⁽¹⁾	2	400
400 miletelitial hear to hear thical (1)	3	600
	4	800
	5	1000

Note:

(1) Refer to Figure 4.

Page 38 Switching Characteristics

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

	Performance								
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit					
Global and Regional Clock	717	650	580	MHz					
Periphery Clock	550	500	500	MHz					

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 4 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY	C4,I4			Unit
Symbol	Conuntions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Ullit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)		(8)	(6)		(8)	(6)	_	(8)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)		(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
DPA Mode														
DPA run length	_		_	1000 0			1000 0	_		1000 0	_	_	1000 0	UI
Soft CDR mode	•													
Soft-CDR PPM tolerance	_	_	_	300	_	_	300	_	_	300	_	_	300	± PPM
Non DPA Mode	,													
Sampling Window	_	_	_	300	_		300	_		300	_	_	300	ps

Notes to Table 36:

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Page 48 Switching Characteristics

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled

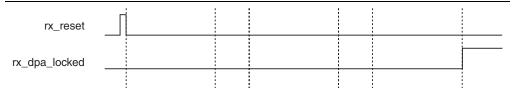


Table 37 lists the DPA lock time specifications for Stratix V devices.

Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only (1), (2), (3)

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽⁴⁾	Maximum
SPI-4	0000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
Farallel hapiu 1/0	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
IVIISCEIIAIIEOUS	01010101	8	32	640 data transitions

Notes to Table 37:

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in this table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the **LVDS** soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate \geq 1.25 Gbps. Table 38 lists the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate \geq 1.25 Gbps.

Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate \geq 1.25 Gbps

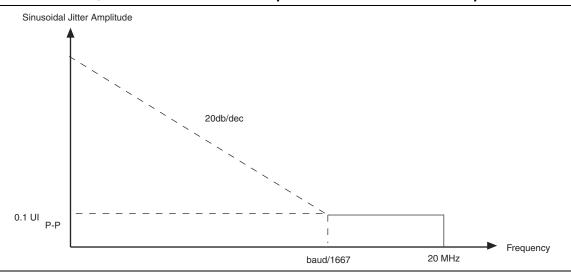
LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification

Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate \geq 1.25 Gbps

Jitter Fr	equency (Hz)	Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.

Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

Page 62 Configuration Specification

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + (8576 \times \\ \text{CLKUSR period}) \end{array}$	_	_

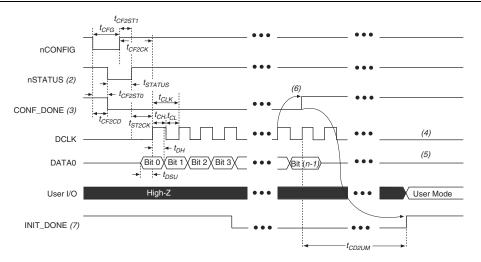
Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Page 64 I/O Timing

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit	
t _{RU_nCONFIG} (1)	250	_	ns	
t _{RU_nRSTIMER} (2)	250	_	ns	

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units	
5.3	7.9	12.5	MHz	

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Doromotor	Aveilable Min		Fast Model		Slow Model							
Parameter (1)	Available Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Page 68 Glossary

Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions			
	V _{CM(DC)}	DC common mode input voltage.			
	V _{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.			
	V _{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.			
	V _{DIF(AC)}	AC differential input voltage—Minimum AC input differential voltage required for switching.			
	V _{DIF(DC)}	DC differential input voltage— Minimum DC input differential voltage required for switching.			
	V _{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.			
	V _{IH(AC)}	High-level AC input voltage			
	V _{IH(DC)}	High-level DC input voltage			
V	V _{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.			
	V _{IL(AC)}	Low-level AC input voltage			
	V _{IL(DC)}	Low-level DC input voltage			
	V _{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.			
	V _{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.			
	V _{SWING}	Differential input voltage			
	V _X	Input differential cross point voltage			
	V _{OX}	Output differential cross point voltage			
W	W	High-speed I/O block—clock boost factor			
Χ					
Υ		_			
Z					